

Basic information**2018/2947(DEA)**

DEA - Delegated acts procedure

Exemption for lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

Supplementing [2008/0240\(COD\)](#)**Subject**

3.40.06 Electronics, electrotechnical industries, ICT, robotics
3.70.13 Dangerous substances, toxic and radioactive wastes (storage, transport)

Procedure completed - delegated act enters into force

Additional information

Source	Document	Date
European Commission	EUR-Lex	